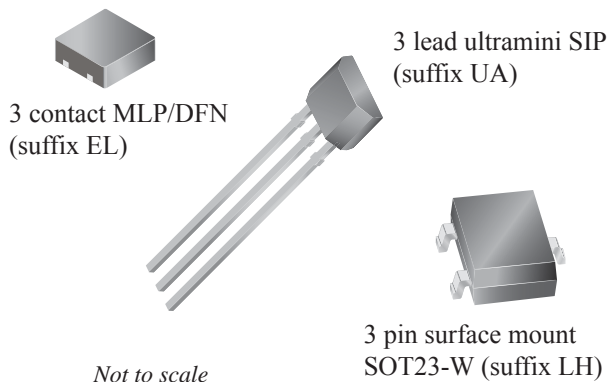


Micropower Ultra-Sensitive Hall-Effect Switches

Features and Benefits

- Micropower operation
- Operate with north or south pole
- 2.4 to 5.5 V battery operation
- Chopper stabilized
 - Superior temperature stability
 - Extremely low switchpoint drift
 - Insensitive to physical stress
- High ESD protection
- Solid state reliability
- Small size
- Easily assembly into applications due to magnetic pole independence

Packages



Description

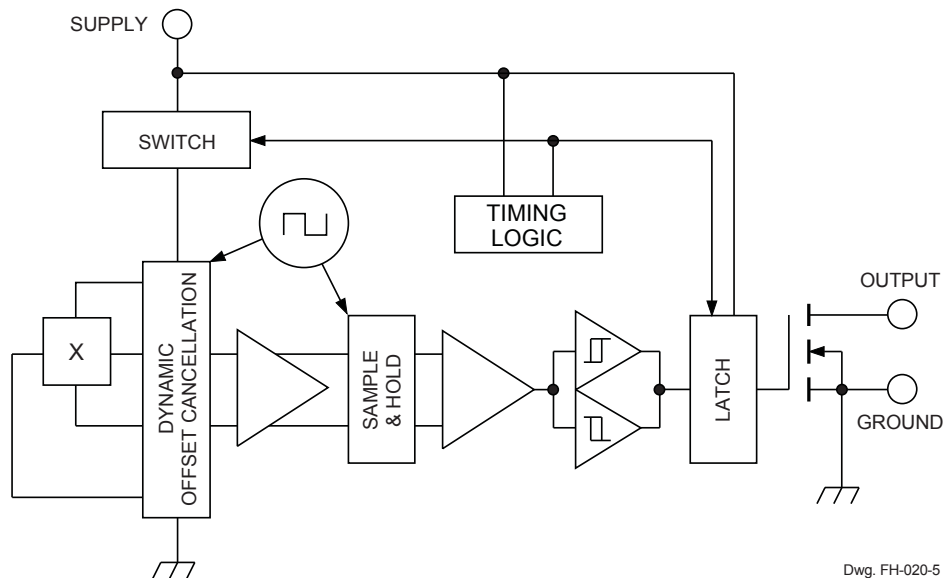
The A3213 and A3214 integrated circuits are ultra-sensitive, pole independent Hall-effect switches with a latched digital output. They are especially suited for operation in battery-operated, hand-held equipment such as cellular and cordless telephones, pagers, and palmtop computers. A 2.4 to 5.5 V operation and a unique clocking scheme reduce the average operating power requirements – the A3213 to 825 μW , the A3214 to 14 μW (typical, at 2.75 V)! Except for operating duty cycle and average operating current, the A3213 and A3214 are identical.

Unlike other Hall-effect switches, either a north or south pole of sufficient strength will turn the output on; in the absence of a magnetic field, the output is off. The polarity independence and minimal power requirement allows these devices to easily replace reed switches for superior reliability and ease of manufacturing, while eliminating the requirement for signal conditioning.

Improved stability is made possible through chopper stabilization (dynamic offset cancellation), which reduces the residual offset voltage normally caused by device overmolding, temperature dependencies, and thermal stress.

Continued on the next page...

Functional Block Diagram



Dwg. FH-020-5

Description (continued)

These devices include, on a single silicon chip, a Hall-voltage generator, small-signal amplifier, chopper stabilization, a latch, and a MOSFET output. Advanced BiCMOS processing is used to take advantage of low-voltage and low-power requirements, component matching, very low input-offset errors, and small component geometries.

Range 'E' devices are rated for operation over a temperature range of -40°C to 85°C; range 'L' devices are rated for operation over a

temperature range of -40°C to 150°C. Two package styles provide a magnetically optimized package for most applications. 'LH' is a miniature low-profile surface-mount package, 'UA' is a three-lead SIP for through-hole mounting. For the A3213, a microleadless DFN/MLP package 'EL' also is available. Each package is available in a lead (Pb) free version (suffix, -T), with a 100% matte tin plated leadframe.



Product Selection Guide

| Part Number | Mounting | Packing ¹ | Ambient, T _A (°C) | DC (%) | I _{DDAVG(TYP)} (μA) |
|-------------------------------------|--------------------------------|--------------------------------|---------------------------------|-----------|---------------------------------|
| A3213EELLT-T | EL package Surface mount | 7-in. reel 3000 pieces/reel | -40 to 85 | 25 | 460 |
| A3213ELHLT-T | LH package Surface Mount | | | | |
| A3213EUA-T | UA package SIP through hole | Bulk 500 pieces/bag | | | |
| A3213LLHLT-T² | LH package Surface Mount | 7-in. reel 3000 pieces/reel | -40 to 150 | 0.10 | 11 |
| A3213LUA-T² | UA package SIP through hole | Bulk 500 pieces/bag | | | |
| A3214ELHLT-T | LH package Surface Mount | 7-in. reel 3000 pieces/reel | -40 to 85 | | |
| A3214LLHLT-T² | LH package Surface Mount | 7-in. reel 3000 pieces/reel | -40 to 150 | | |
| A3214LUA-T² | UA package SIP through hole | Bulk 500 pieces/bag | | | |

¹Contact Allegro for additional packing options.

²These variants are in production, however, they have been deemed Pre-End of Life. The products are approaching end of life. Within a minimum of 6 months, these devices will enter their final, Last Time Buy, order phase. For a currently available next generation replacement part: for the A3213LLHLT-T use the A3213ELHLT-T, for the A3213LUA-T use the A3213EUA-T, for the A3214LLHLT-T use the A3214ELHLT-T, and for the A3214LUA-T use the A3214EUA-T; the A3214EUA-T will be added to our web site and will be available for sampling by the end of April 2011. Status change: March 8, 2011.

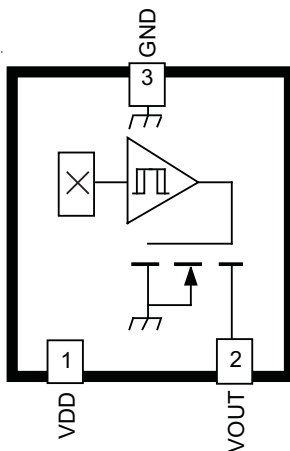
Absolute Maximum Ratings

| Characteristic | Symbol | Notes | Rating | Units |
|-------------------------------|--------------|---------|------------|-------|
| Supply Voltage | V_{DD} | | 6 | V |
| Magnetic Flux Density | B | | Unlimited | G |
| Output Off Voltage | V_{OUT} | | 6 | V |
| Output Current | I_{OUT} | | 1 | mA |
| Operating Ambient Temperature | T_A | Range E | -40 to 85 | °C |
| | | Range L | -40 to 150 | °C |
| Maximum Junction Temperature | $T_{J(max)}$ | | 165 | °C |
| Storage Temperature | T_{stg} | | -65 to 170 | °C |

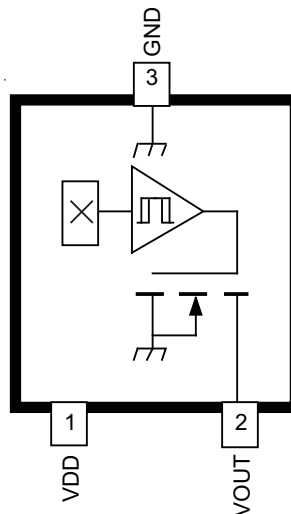
Pin-out Diagrams

| Number | | Name | Description |
|--------|----|------|--|
| EL, LH | UA | | |
| 1 | 1 | VDD | Input power supply; tie to GND with bypass capacitor |
| 3 | 2 | GND | Ground |
| 2 | 3 | VOUT | Output signal |

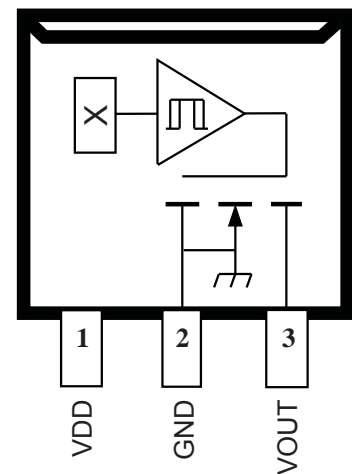
EL Package



LH Package



UA Package



ELECTRICAL CHARACTERISTICS valid over operating voltage and temperature range, unless otherwise noted

| Characteristic | Symbol | Test Conditions | Min. | Typ. ¹ | Max. | Units |
|------------------------|----------------------|---|------|-------------------|------|-------|
| Supply Voltage Range | V _{DD} | Operating ¹) | 2.4 | 3.0 | 5.5 | V |
| Output Leakage Current | I _{OFF} | V _{OUT} = 5.5 V, B _{RPN} < B < B _{RPS} | – | <1.0 | 1.0 | μA |
| Output On Voltage | V _{OUT} | I _{OUT} = 1 mA, V _{DD} = 3.0 V | – | 100 | 300 | mV |
| Awake Time | t _{awake} | | – | 60 | 90 | μs |
| Period | t _{period} | A3213 | – | 240 | 360 | μs |
| | | A3214, T _A = 25°C, V _{DD} = 3 V | – | 60 | 90 | ms |
| Duty Cycle | DC | A3213 | – | 25 | – | % |
| | | A3214 | – | 0.10 | – | % |
| Chopping Frequency | f _C | | – | 340 | – | kHz |
| Supply Current | I _{DD(EN)} | Chip awake (enabled) | – | – | 2.0 | mA |
| | I _{DD(DIS)} | Chip asleep (disabled) | – | – | 8.0 | μA |
| | I _{DD(AVG)} | A3213 | – | 460 | 850 | μA |
| | | A3214 | – | 11 | 22 | μA |

¹Typical Data is at T_A = 25°C and V_{DD} = 3.0 V and is for design information only.

²Operate and release points will vary with supply voltage. B_{OPx} = operate point (output turns ON); B_{RPx} = release point (output turns OFF).

MAGNETIC CHARACTERISTICS valid over operating voltage and temperature range, unless otherwise noted¹

| Characteristic | Symbol ² | Test Conditions | Min. | Typ. ³ | Max. | Units ⁴ |
|----------------|---------------------|-------------------------------------|------|-------------------|------|--------------------|
| Operate Points | B _{OPS} | South pole to branded side | – | 42 | 70 | G |
| | B _{OPN} | North pole to branded side | –70 | –48 | – | G |
| Release Points | B _{RPS} | South pole to branded side | 10 | 32 | – | G |
| | B _{RPN} | North pole to branded side | – | –38 | –10 | G |
| Hysteresis | B _{hys} | B _{OPx} - B _{RPx} | – | 10 | – | G |

¹As used here, negative flux densities are defined as less than zero (algebraic convention) and -50 G is less than +10 G.

²B_{OPx} = operate point (output turns ON); B_{RPx} = release point (output turns OFF).

³Typical Data is at T_A = 25°C and V_{DD} = 3.0 V and is for design information only.

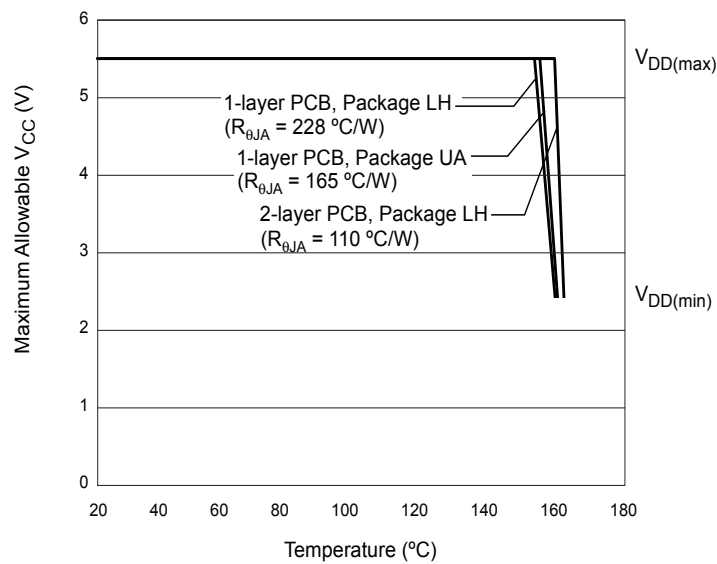
⁴1 gauss (G) is exactly equal to 0.1 millitesla (mT).

Thermal characteristics may require derating at maximum conditions, see application information

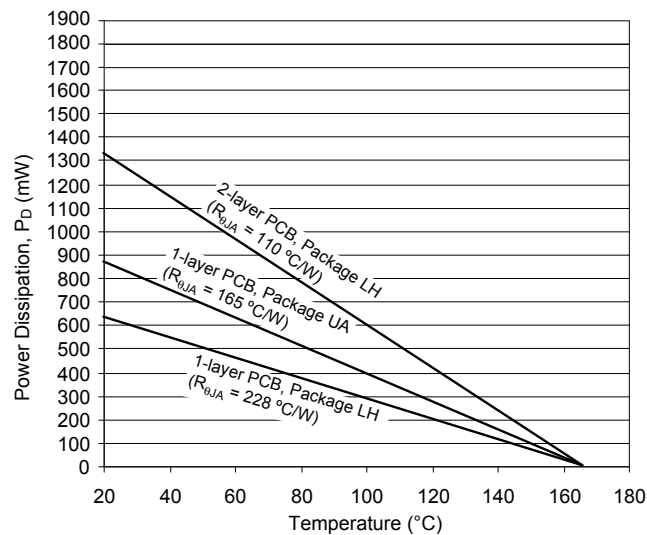
| Characteristic | Symbol | Test Conditions* | Value | Units |
|----------------------------|-----------------|--|-------|-----------------------------|
| Package Thermal Resistance | $R_{\theta JA}$ | Package LH, 1-layer PCB with copper limited to solder pads | 228 | $^{\circ}\text{C}/\text{W}$ |
| | | Package LH, 2-layer PCB with 0.463 in. ² of copper area each side connected by thermal vias | 110 | $^{\circ}\text{C}/\text{W}$ |
| | | Package UA, 1-layer PCB with copper limited to solder pads | 165 | $^{\circ}\text{C}/\text{W}$ |

*Additional thermal information available on Allegro website.

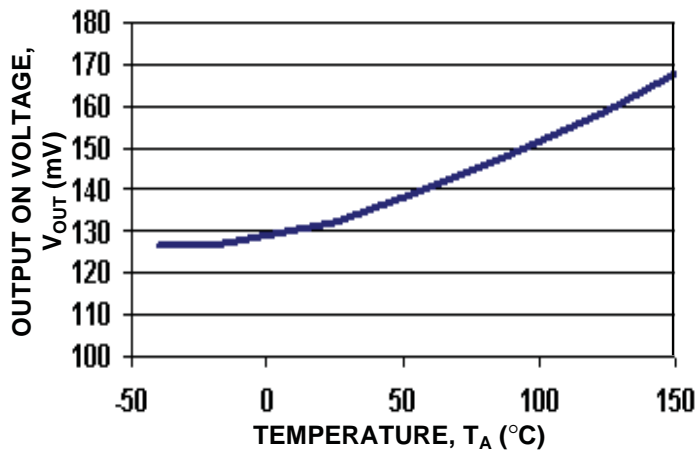
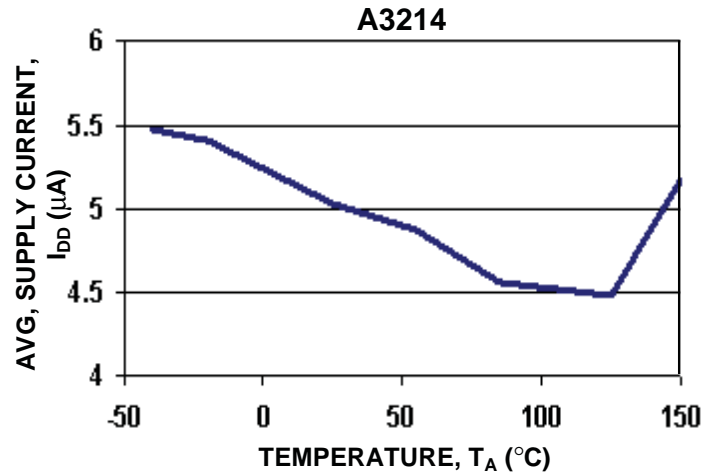
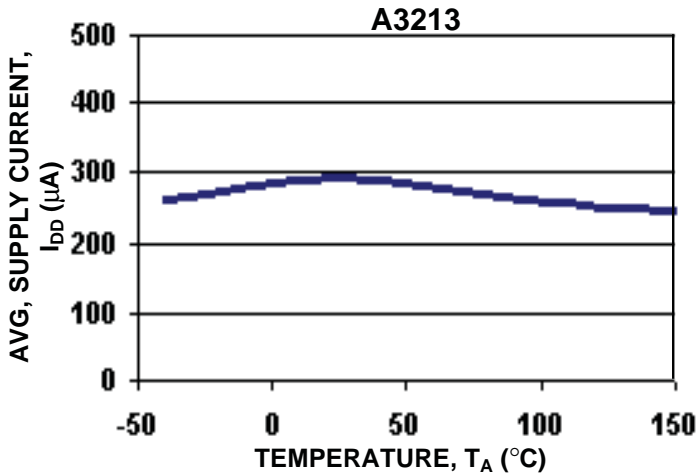
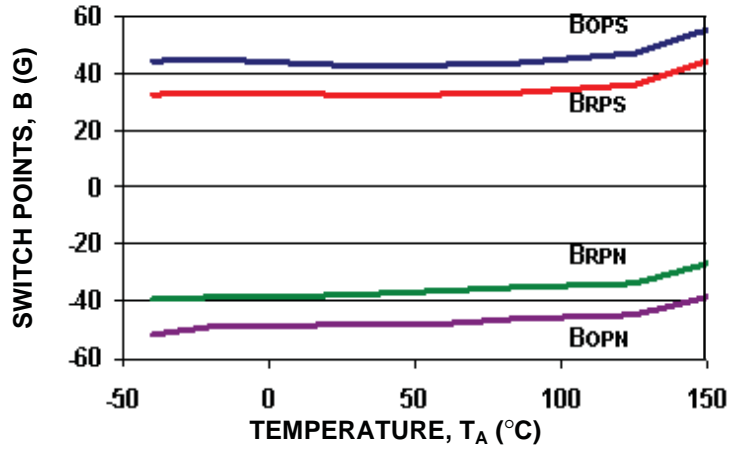
Power Derating Curve



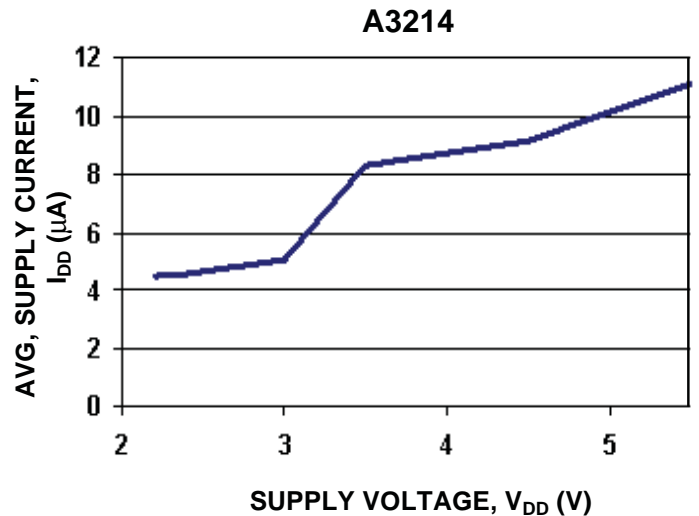
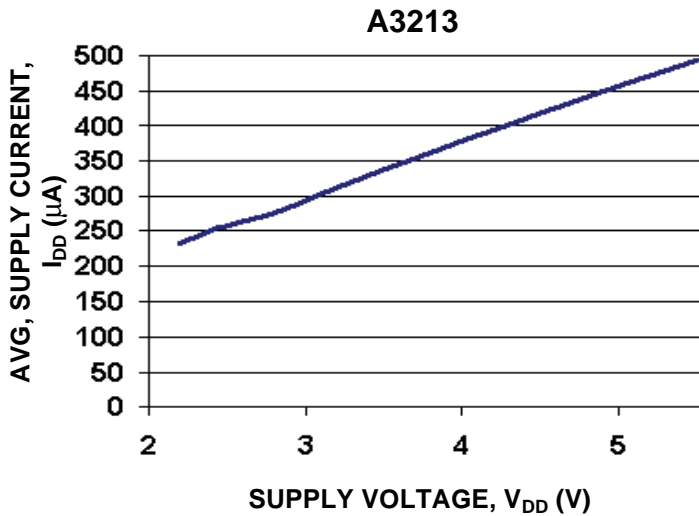
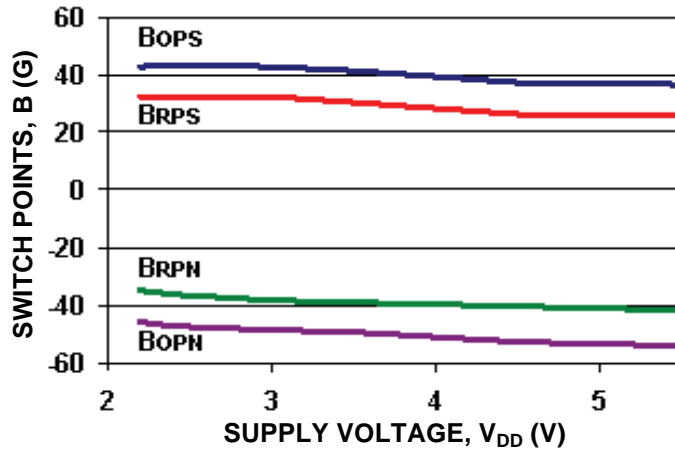
Power Dissipation versus Ambient Temperature



**TYPICAL OPERATING CHARACTERISTICS
as a function of temperature ($V_{DD} = 3\text{ V}$)**

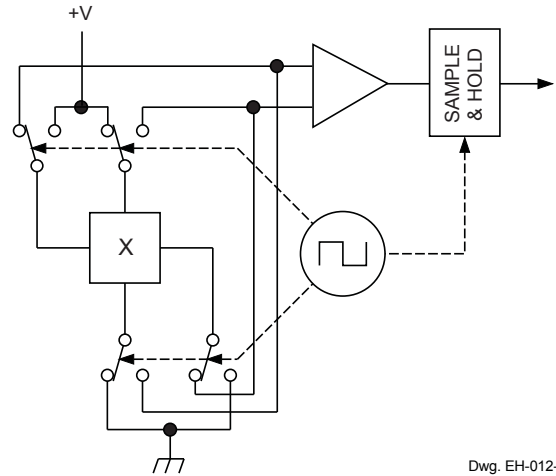
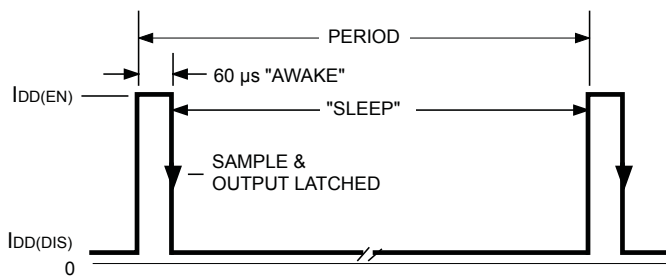


**TYPICAL OPERATING CHARACTERISTICS
as a function of supply voltage ($T_A = 25^\circ\text{C}$)**



FUNCTIONAL DESCRIPTION

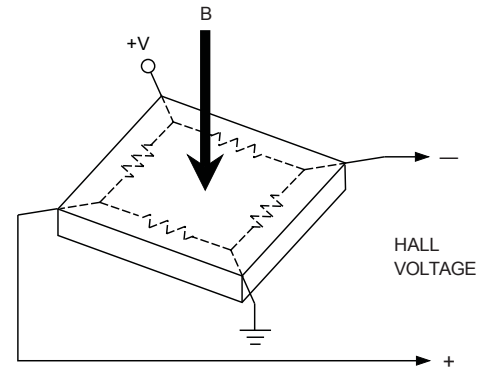
Low Average Power. Internal timing circuitry activates the IC for 60 μ s and deactivates it for the remainder of the period (240 μ s for the A3213 and 60 ms for the A3214). A short "awake" time allows for stabilization prior to the sampling and data latching on the falling edge of the timing pulse. The output during the "sleep" time is latched in the last sampled state. The supply current is not affected by the output state.



Dwg. EH-012-1

Chopper-Stabilized Technique. The Hall element can be considered as a resistor array similar to a Wheatstone bridge. A large portion of the offset is a result of the mismatching of these resistors. These devices use a proprietary dynamic offset cancellation technique, with an internal high-frequency clock to reduce the residual offset voltage of the Hall element that is normally caused by device overmolding, temperature dependencies, and thermal stress. The chopper-stabilizing technique cancels the mismatching of the resistor circuit by changing the direction of the current flowing through the Hall plate using CMOS switches and Hall voltage measurement taps, while maintaining the Hall-voltage signal that is induced by the external magnetic flux. The signal is then captured by a sample-and-hold circuit and further processed using low-offset bipolar circuitry. This technique produces devices that have an extremely stable quiescent Hall output voltage, are immune to thermal stress, and have precise recoverability after temperature cycling. This technique will also slightly degrade the device output repeatability. A relatively high sampling frequency is used in order that faster signals can be processed.

More detailed descriptions of the circuit operation can be found in Technical Paper STP 97-10, *Monolithic Magnetic Hall Sensing Using Dynamic Quadrature Offset Cancellation* and Technical Paper STP 99-1, *Chopper-Stabilized Amplifiers With A Track-and-Hold Signal Demodulator*.



Dwg. AH-011-2

Operation. The output of this device switches low (turns on) when a magnetic field perpendicular to the Hall element exceeds the operate point B_{OPS} (or is less than B_{OPN}). After turn-on, the output is capable of sinking up to 1 mA and the output voltage is $V_{OUT(ON)}$. When the magnetic field is reduced below the release point B_{RPS} (or increased above B_{RPN}), the device output switches high (turns off). The difference in the magnetic operate and release points is the hysteresis (B_{hys}) of the device. This built-in hysteresis allows clean switching of the output even in the presence of external mechanical vibration and electrical noise.

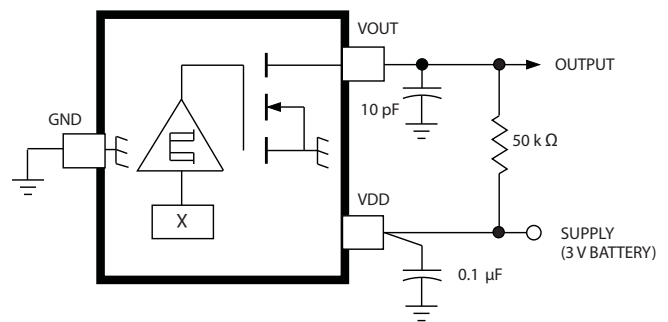
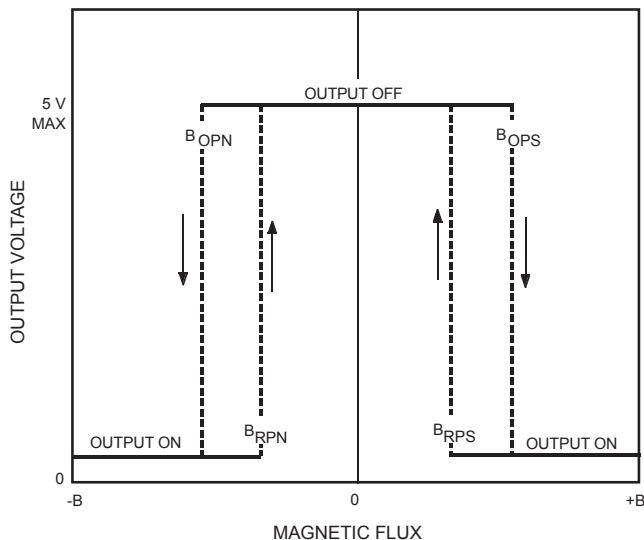
As used here, negative flux densities are defined as less than zero (algebraic convention) and -50 G is less than +10 G.

Applications. Allegro's pole-independent sensing technique allows for operation with either a north pole or south pole magnet orientation, enhancing the flexibility of the device in application assembling. The state-of-the-art technology provides the same output polarity for either pole face.

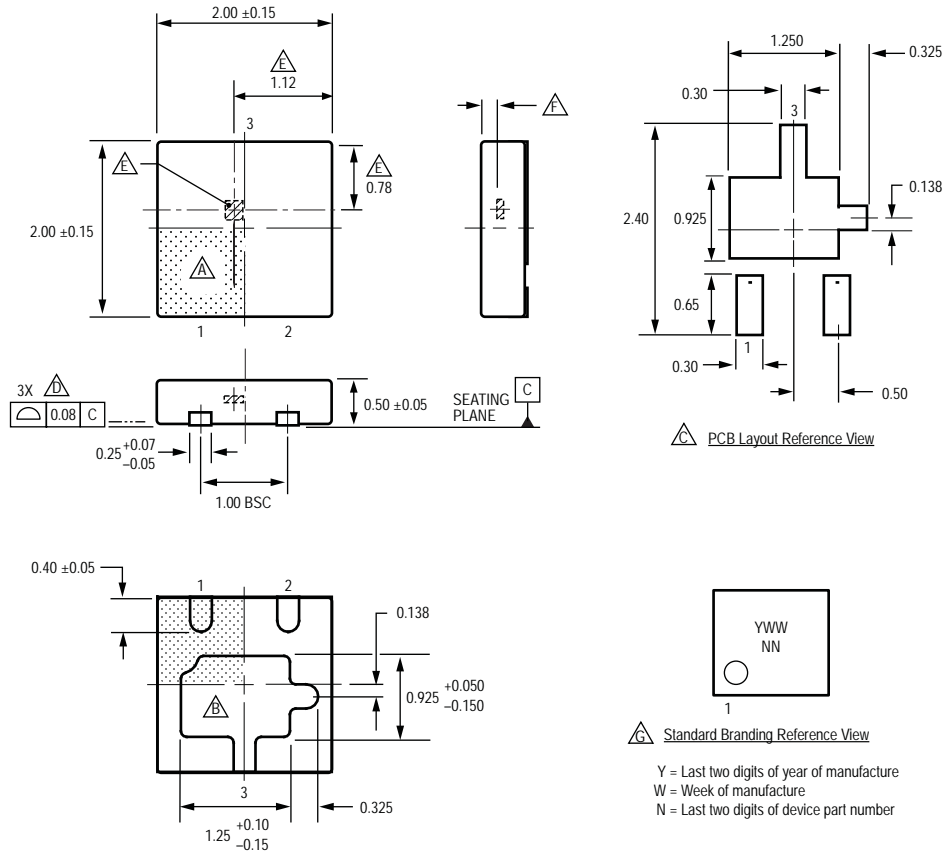
It is strongly recommended that an external bypass capacitor be connected (in close proximity to the Hall element) between the supply and ground of the device to reduce both external noise and noise generated by the chopper-stabilization technique. This is especially true due to the relatively high impedance of battery supplies.

The simplest form of magnet that will operate these devices is a bar magnet with either pole near the branded surface of the device. Many other methods of operation are possible. Extensive applications information on magnets and Hall-effect devices is also available in the *Allegro Electronic Data Book AMS-702* or *Application Note 27701*, or at

www.allegromicro.com



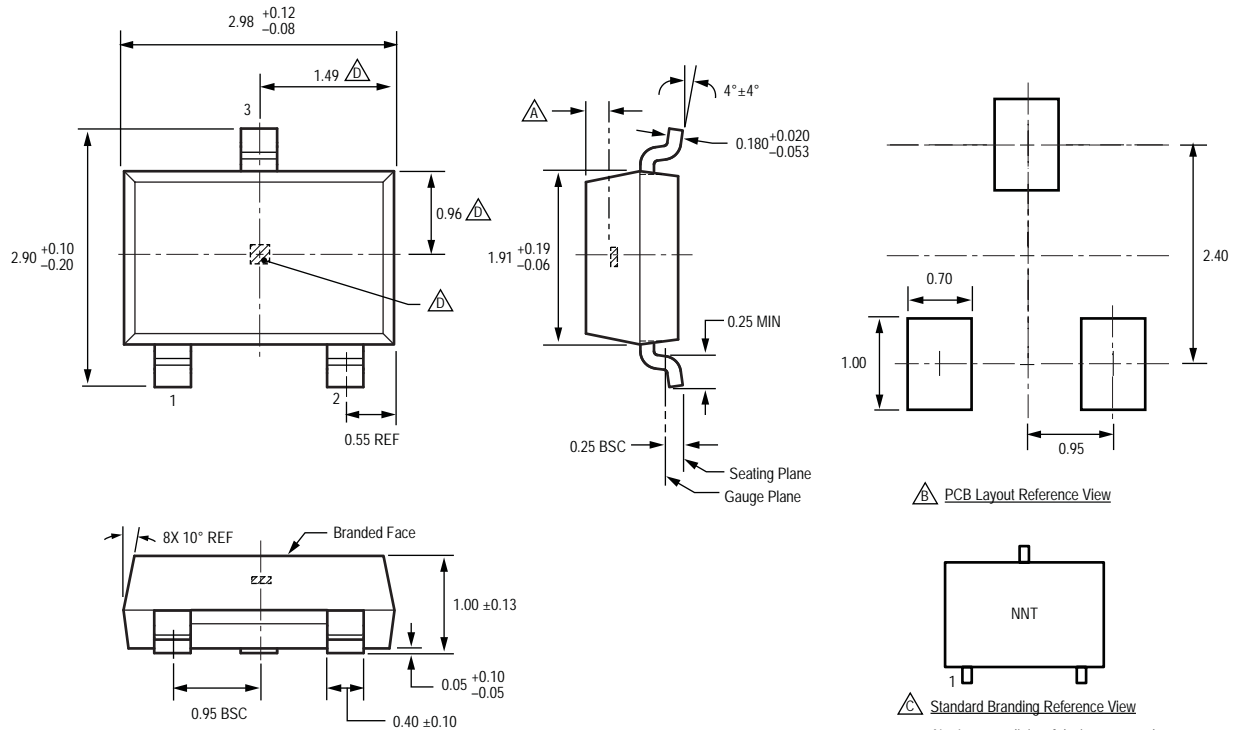
Package EL, 3-Contact MLP/DFN



For Reference Only, not for tooling use (reference DWG-2865;
reference JEDEC MO-229UCCD)
Dimensions in millimeters
Exact case and lead configuration at supplier discretion within limits shown

- △ Terminal #1 mark area
- △ Exposed thermal pad (reference only, terminal #1 identifier appearance at supplier discretion)
- △ Reference land pattern layout (reference IPC7351); All pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)
- △ Coplanarity includes exposed thermal pad and terminals
- △ Hall Element (not to scale)
- △ Active Area Depth, 0.18 mm NOM
- △ Branding scale and appearance at supplier discretion

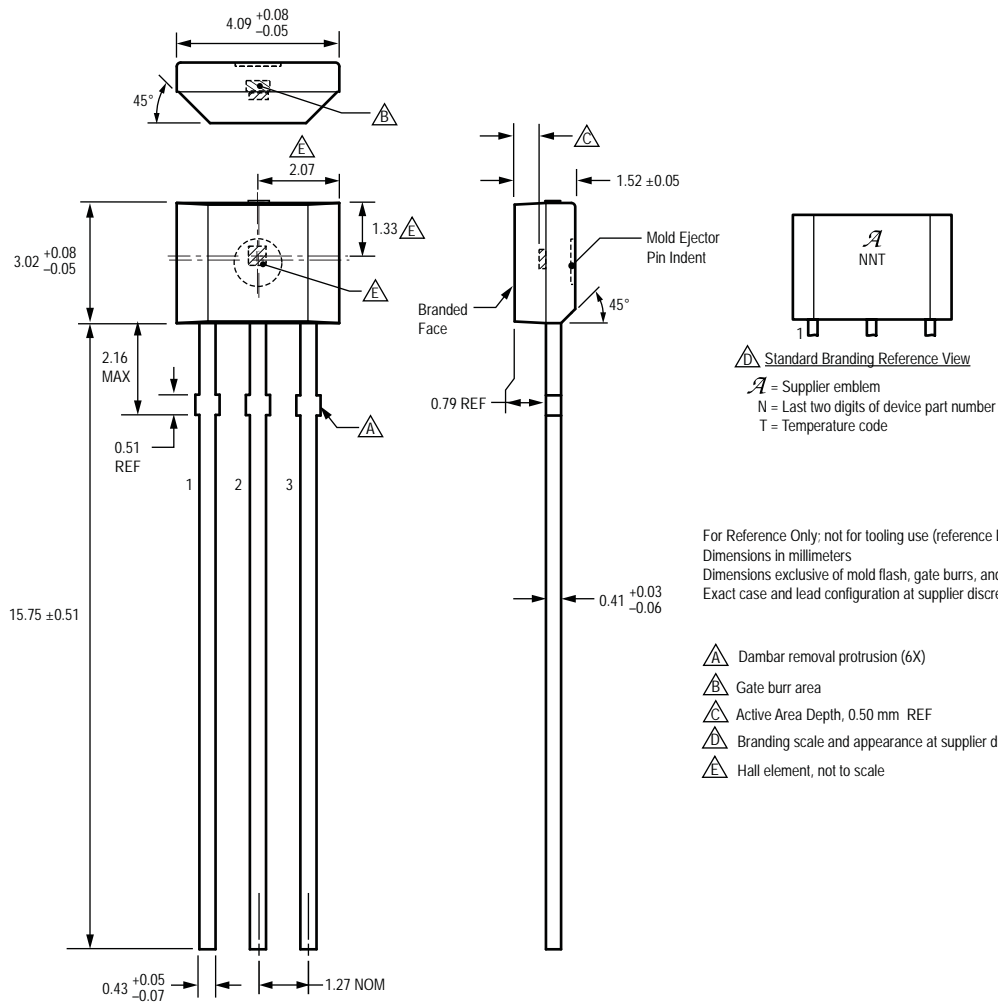
Package LH, 3-Pin (SOT-23W)



- For Reference Only; not for tooling use (reference dwg. 802840)
 Dimensions in millimeters
 Dimensions exclusive of mold flash, gate burrs, and dambar protrusions
 Exact case and lead configuration at supplier discretion within limits shown
- \triangle Active Area Depth, 0.28 mm REF
 - \triangle Reference land pattern layout
 All pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances
 - \triangle Branding scale and appearance at supplier discretion
 - \triangle Hall element, not to scale

\triangle PCB Layout Reference View
 \triangle Standard Branding Reference View
 N = Last two digits of device part number
 T = Temperature code

Package UA, 3-Pin SIP



Revision History

| Revision | Revision Date | Description of Revision |
|-----------------|----------------------|--------------------------------|
| Rev. R | March 8, 2011 | Update product availability |
| | | |

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